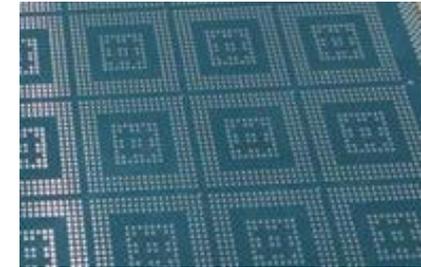


SMART-B1640III

Chip of IC
IC晶片

Material	工件材質	Silicon Carbide (碳化矽)
Hardness	工件硬度	HRC20
Machining Size	加工尺寸	305x800mm(WxH)
Machining Time	加工時間	8.5min / 8.5分



Point of Requirement 需求重點

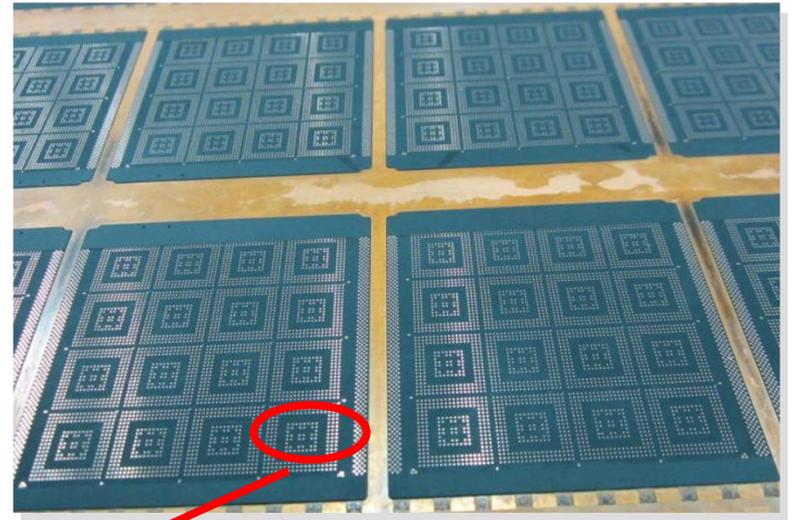
10

It takes you only 10 mins to manage to use auto probe and compensation by smart grinders with high efficiency and total solution.

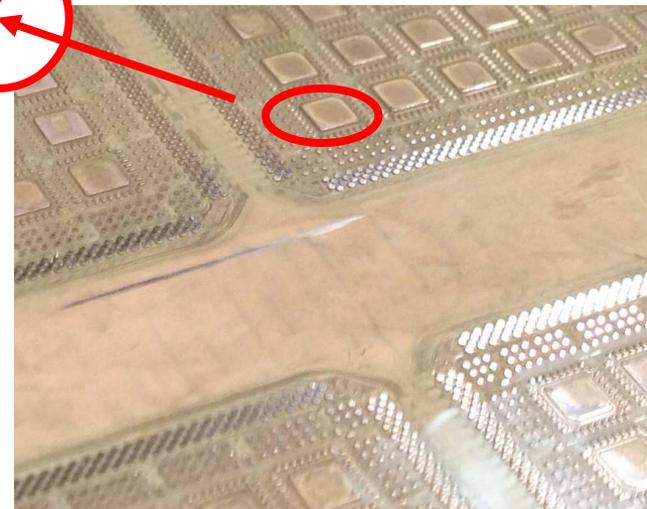
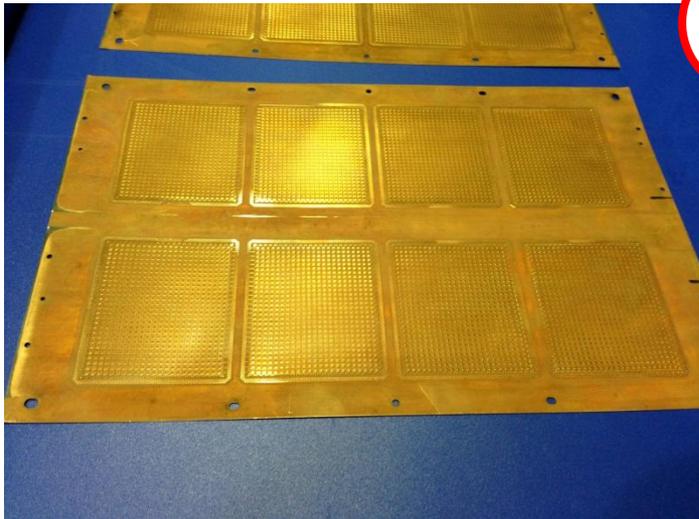
SMART 自動量測與補正之速成與高效能與完整解決方案

Point of Requirement / 需求重點	Specifications or Accuracy / 規格或精度
Grinding Wheel / 砂輪型式	GC-320-H-10-V (Brand:Kinik Taiwan)
Demension Accuracy / 尺寸精度	±0.008mm
Surface Roughness / 工件粗度	Ra 0.2 μ m

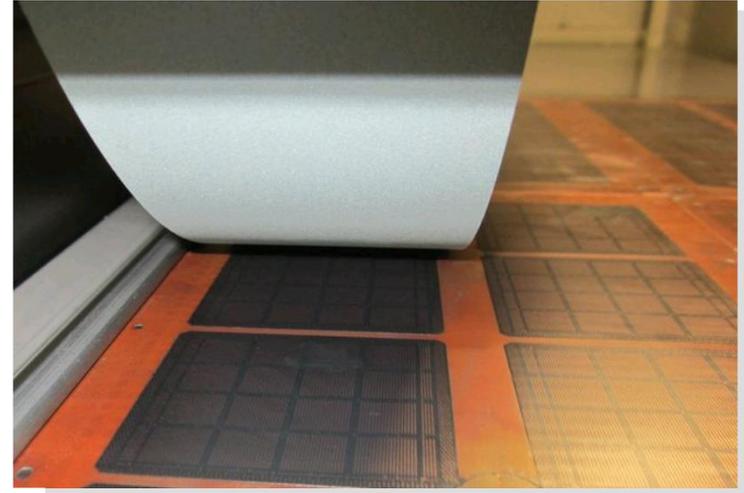
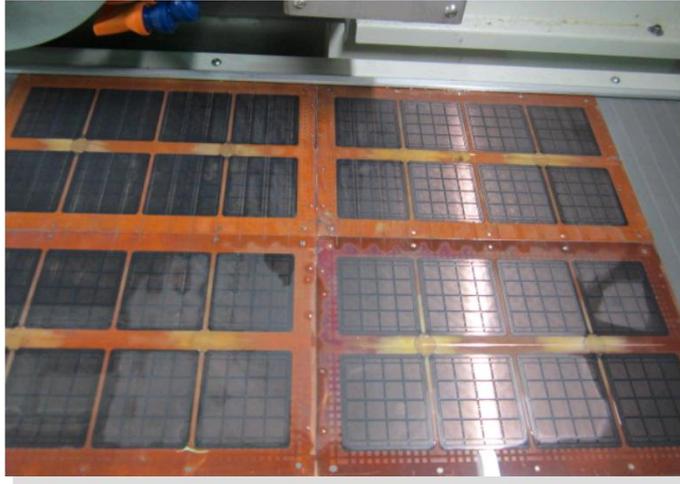
10. Chip of IC / IC晶片



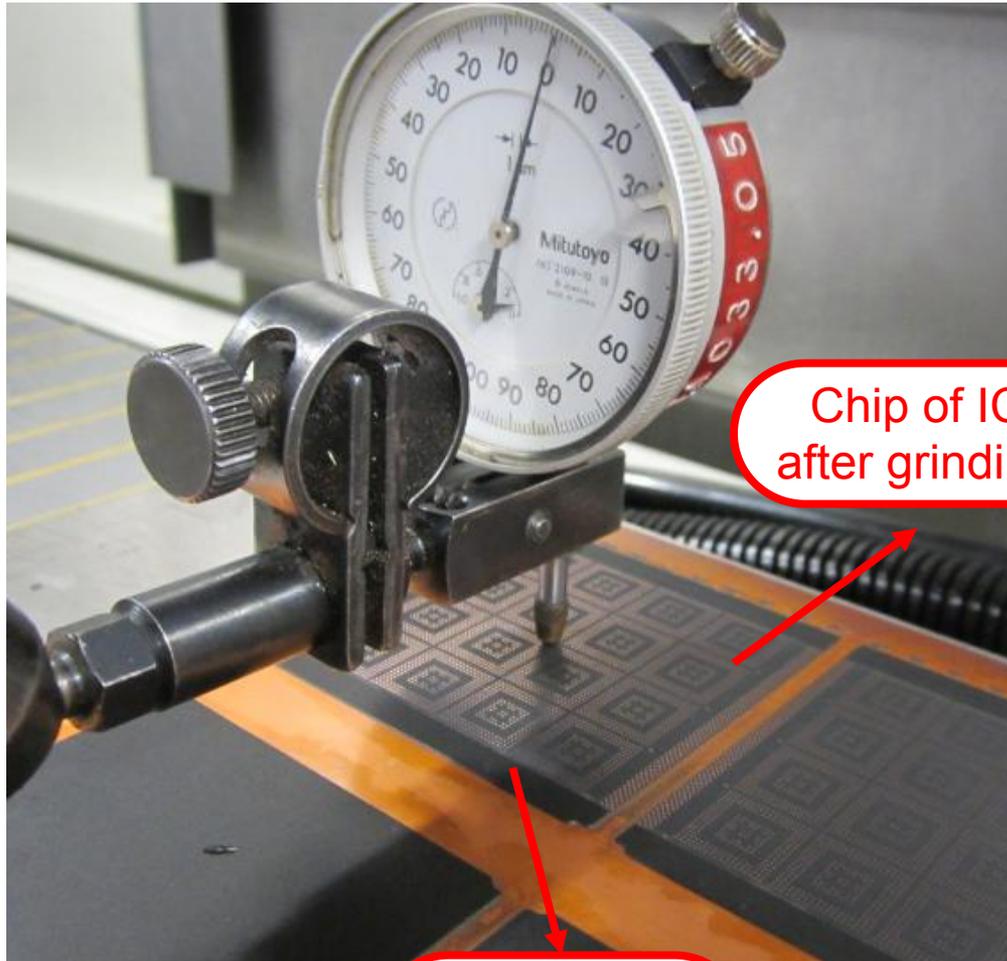
Chip of IC
IC晶片



10. Chip of IC / IC晶片

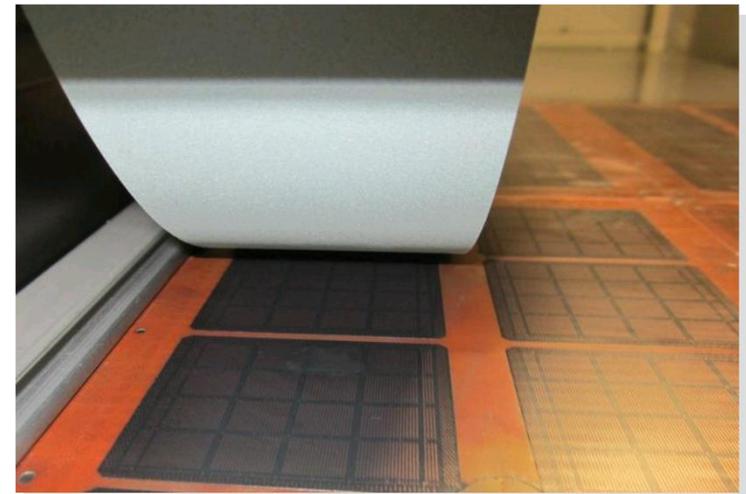
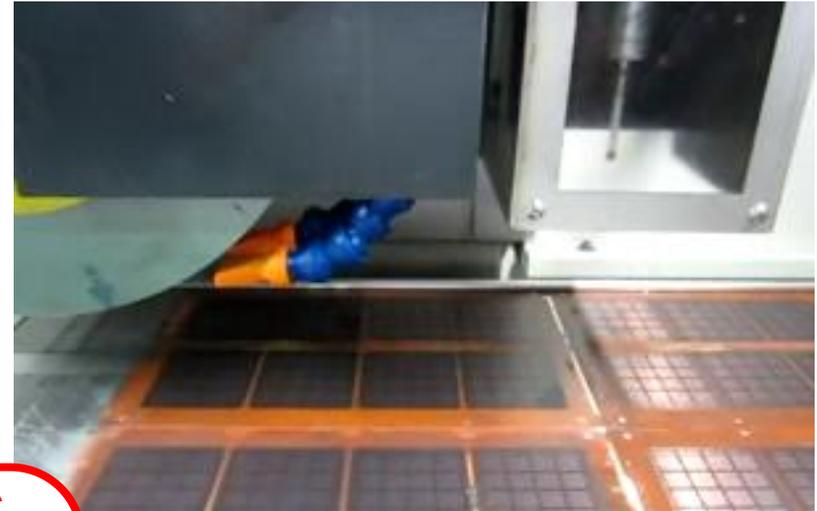


10. Chip of IC / IC晶片



Chip of IC
after grinding

Chip of IC
Before grinding



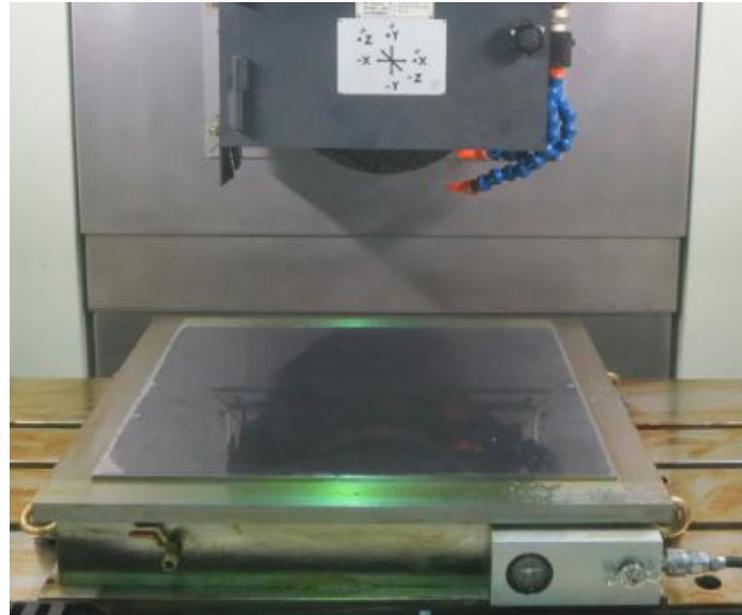
10. Chip of IC / IC晶片

材料：
環氧樹脂 (Epoxy)

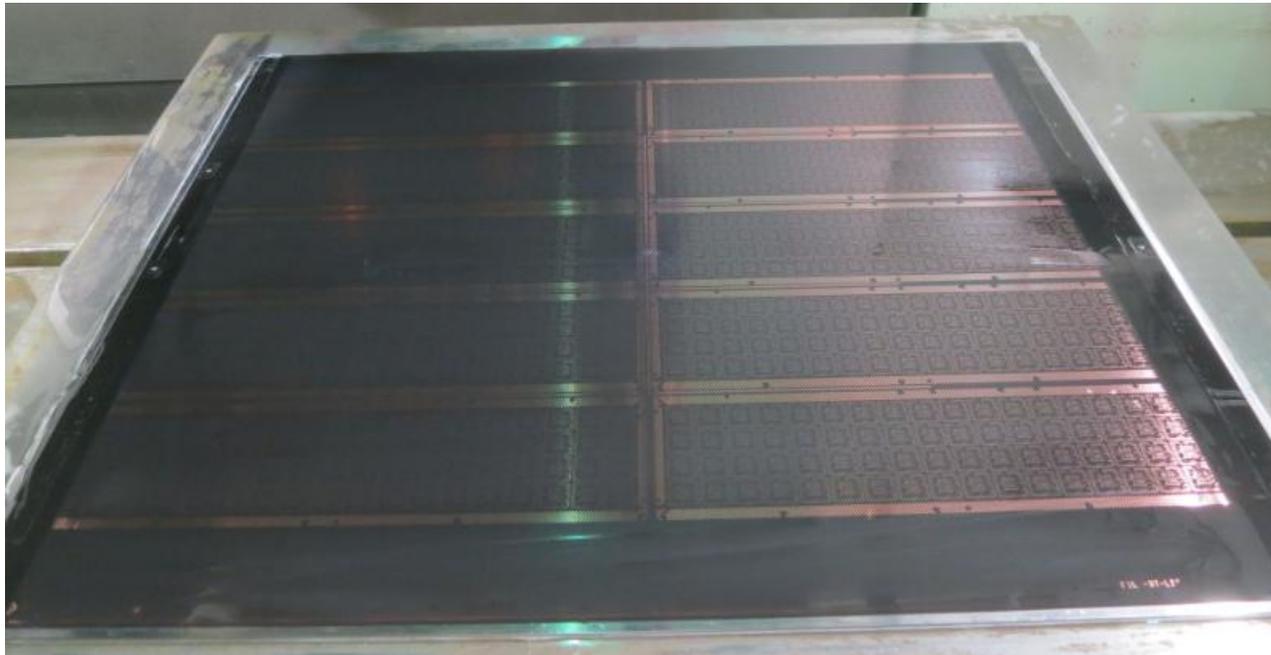
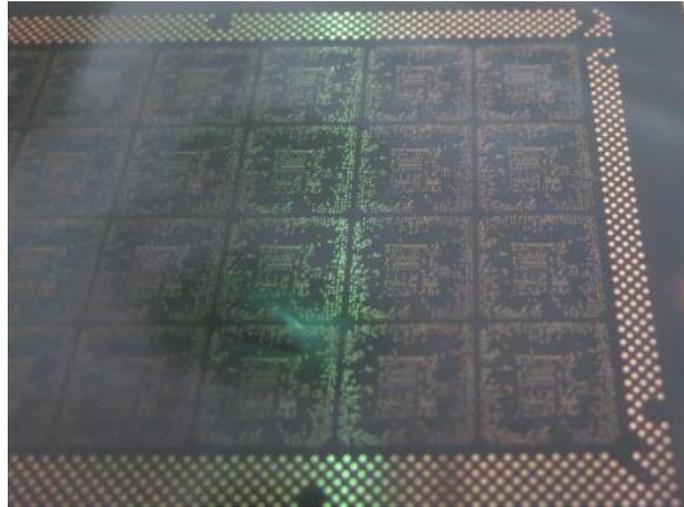
材料隨著半導體構裝的功能複雜性與小型化、高密度的提升，且顧及到低功率損失等特性，載板的線寬/線距亦隨之朝細線化演進。再從載板結構的製程比較：隨著半導體模組封裝的元件內容越來越多，從單一種 IC 的疊構，到多種 IC 的堆疊，從垂直導通的連結，深化到內埋元件的載板 (Embedded Substrate)，系統封裝 (System in Package 簡稱 SiP) 用模組載板所內埋的已經不只單一被動元件。

對於半導體整體構裝而言，薄化能力是電子產品組裝追求的方向，半導體構裝材料的可靠性隨著 IC 要導入車用電子、穿戴式裝置、或是置於極端環境下的物聯網 (IoT) 產品時，尤其對載板的可靠性要求也會隨之提高，散熱性是最近下游構裝廠強調的趨勢與需求。

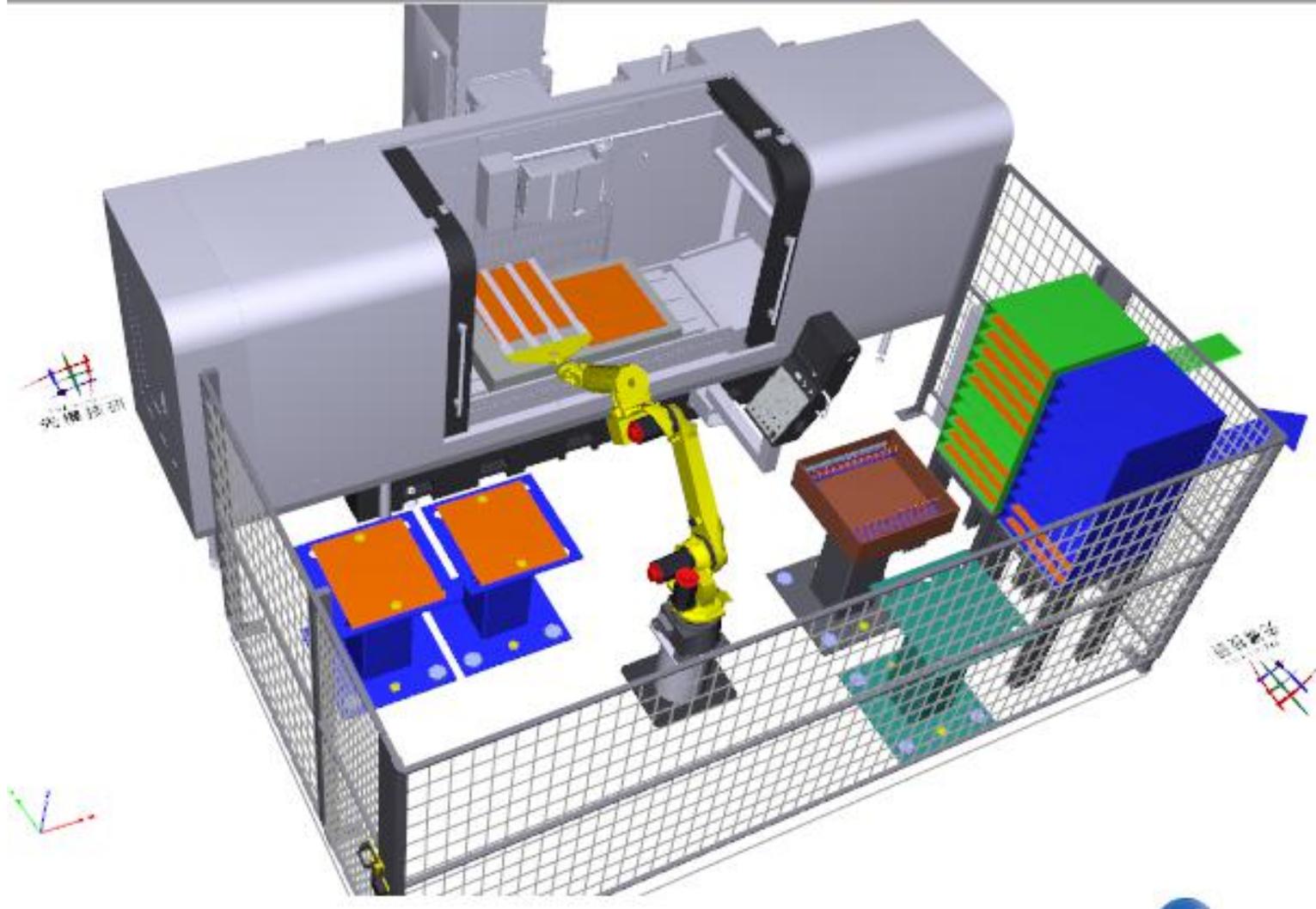
10. Chip of IC / IC晶片



10. Chip of IC / IC晶片



10. Chip of IC / IC晶片



10. Chip of IC / IC晶片

